Unitrode Products from Texas Instruments

application INFO available

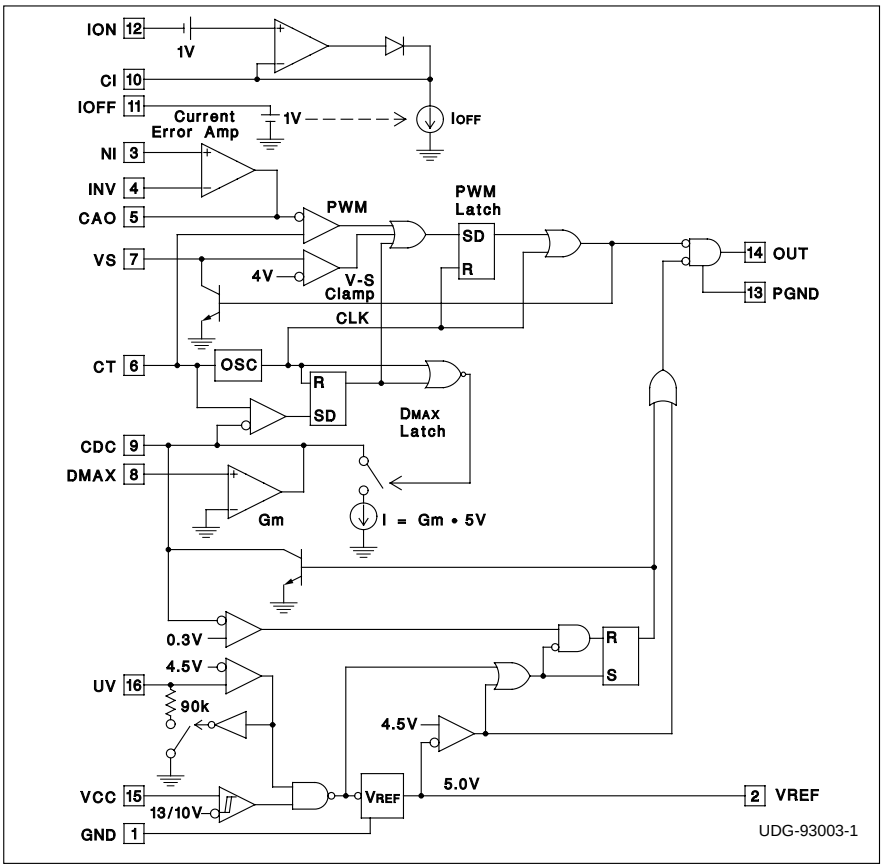
UC1848
UC2848
UC3848

Average Current Mode PWM Controller

FEATURES

- Practical Primary Side Control of Isolated Power Supplies with DC Control of Secondary Side Current
- Accurate Programmable Maximum Duty Cycle Clamp
- Maximum Volt-Second Product Clamp to Prevent Core Saturation
- Practical Operation Up to 1MHz
- High Current (2A Pk) Totem Pole Output Driver
- Wide Bandwidth (8MHz) Current Error Amplifier
- Under Voltage Lockout Monitors VCC, VIN and VREF
- Output Active Low During UVLO
- Low Startup Current (500µA)
- Precision 5V Reference (1%)

BLOCK DIAGRAM



DESCRIPTION

The UC3848 family of PWM control ICs makes primary side average current mode control practical for isolated switching converters. Average current mode control insures that both cycle by cycle peak switch current and maximum average inductor current are well defined and will not run away in a short circuit situation. The UC3848 can be used to control a wide variety of converter topologies.

In addition to the basic functions required for pulse width modulation, the UC3848 implements a patented technique of sensing secondary current in an isolated buck derived converter from the primary side. A current waveform synthesizer monitors switch current and simulates the inductor current down slope so that the complete current waveform can be constructed on the primary side without actual secondary side measurement. This information on the primary side allows for full DC control of output current.

The UC3848 circuitry includes a precision reference, a wide bandwidth error amplifier for average current control, an oscillator to generate the system clock, latching PWM comparator and logic circuits, and a high current output driver. The current error amplifier easily interfaces with an optoisolator from a secondary side voltage sensing circuit.

A full featured undervoltage lockout (UVLO) circuit is contained in the UC3848. UVLO monitors the supply voltage to the controller (VCC), the reference voltage (VREF), and the input line voltage (VIN). All three must be good before soft start commences. If either VCC or VIN is low, the supply current required by the chip is only 500µA and the output is actively held low.

Two on board protection features set controlled limits to prevent transformer core saturation. Input voltage is monitored and pulse width is constrained to limit the maximum volt-second product applied to the transformer. A unique patented technique limits maximum duty cycle within 3% of a user programmed value.

These two features allow for more optimal use of transformers and switches, resulting in reduced system size and cost.

Patents embodied in the UC3848 belong to Lambda Electronics Incorporated and are licensed for use in applications employing these devices.

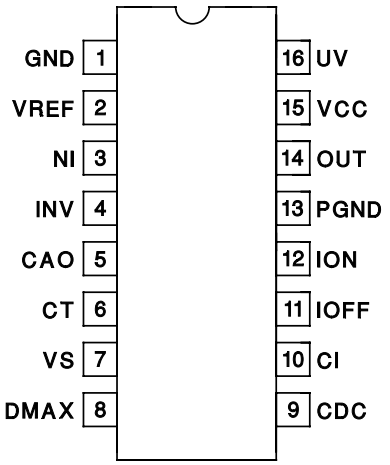
ABSOLUTE MAXIMUM RATINGS

Supply Voltage (Pin 15) 22V
Output Current, Source or Sink (Pin 14)
DC 0.5A
Pulse (0.5 s) 2.2A
Power Ground to Ground (Pin 1 to Pin 13) . . . . . ± 0.2V
Analog Input Voltages
(Pins 3, 4, 7, 8, 12, 16) . . . . . –0.3 to 7V
Analog Input Currents, Source or Sink
(Pins 3, 4, 7, 8, 11, 12, 16) 1mA
Analog Output Currents, Source or Sink (Pins 5 & 10) . . . 5mA
Power Dissipation at TA = 60°C 1W
Storage Temperature Range . . . . . –65°C to +150°C
Lead Temperature (Soldering 10 seconds) . . . . . +300°C

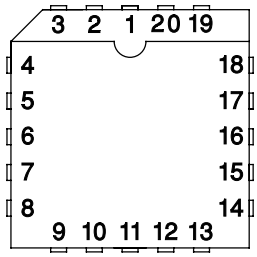
Notes: All voltages are with respect to ground (DIL and SOIC Pin 1). Currents are positive into the specified terminal. Pin numbers refer to the 16 pin DIL and SOIC packages. Consult Packaging Section of Databook for thermal limitations and considerations of packages.

CONNECTION DIAGRAMS

DIL-16, SOIC-16 (Top View)
J, N, or DW Packages



PLCC-20 & LCC-20
(Top View)
Q & L Packages



PACKAGE PIN FUNCTION	
FUNCTION	PIN
N/C	1
GND	2
VREF	3
NI	4
INV	5
N/C	6
CAO	7
CT	8
VS	9
DMAX	10
N/C	11
CDC	12
CI	13
IOFF	14
ION	15
N/C	16
PGND	17
OUT	18
VCC	19
UV	20

THERMAL RATINGS TABLE

Package	Θ_{JA}	Θ_{JC}
DIL-16J	80-120	28(2)
DIL-16N	90(1)	45
SOIC-16DW	50-100(1)	27
PLCC-20	43-75(1)	34
LCC-20	70-80	20(2)(3)

(1) Specified Θ_{JJA} (junction to ambient) is for devices mounted to 5in^2 FR4 PC board with one ounce copper where noted. When resistance range is given, lower values are for 5in^2 aluminum PC board. Test PWB was 0.062in thick and typically used 0.635mm trace widths for power packages and 1.3mm trace widths for non-power packages with 100 x 100 mil probe land area at the end of each trace.

(2)Θ_{JJC} data values stated were derived from MIL-STD-1835B. MIL-STD-1835B states that the baseline values shown are worst case (mean +2s) for a 60 x 60mil microcircuit device silicon die and applicable for devices with die sizes up to 14400 square mils. For device die sizes greater than 14400 square mils use the following values; dual-in-line, 11°C/W; flat pack 10°C/W; pin grid array, 10°C/W.

(3) Θ_{JC} estimated for backside of device, through the metqalized thermal condition pads.

ELECTRICAL CHARACTERISTICS: Unless otherwise stated, all specifications are over the junction temperature range of –55°C to +125°C for the UC1848, –40°C to +85°C for the UC2848, and 0°C to +70°C for the UC3848. Test conditions are: VCC = 12V, CT = 400pF, CI = 100pF, IOFF = 100µA, CDC = 100nF, Cvs = 100pF, and Ivs = 400µA, $T_A = T_J$.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Real Time Current Waveform Synthesizer					
Ion Amplifier					
Offset Voltage		0.95	1	1.05	V
Slew Rate (Note 1)		20	25		V/µs
lib			-2	-20	µA
IOFF Current Mirror					
Input Voltage		0.95	1	1.05	V
Current Gain		0.9	1	1.1	A/A
Current Error Amplifier					
A_{VOL}		60	100		dB
Vio	12V ≤ VCC 20V, 0V VCM 5V			10	mV
lib			-0.5	-3	µA
Voh	I_O = –200µA	3	3.3		V
Vol	I_O = 200µA		0.3	0.6	V
Source Current	V_O = 1V	1.4	1.6	2.0	mA
GBW Product	f = 200kHz	5	8		MHz
Slew Rate (Note 1)		8	10		V/µs
Oscillator					
Frequency	T_A = 25°C	240	250	260	kHz
		235		265	kHz
Ramp Amplitude		1.5	1.65	1.8	V
Duty Cycle Clamp					
Max Duty Cycle	$V(D_{MAX}) = 0.75 \bullet V_{REF}$	73.5	76.5	79.5	%
Volt Second Clamp					
Max On Time		900		1100	ns
VCC Comparator					
Turn-on Threshold			13	14	V
Turn-off Threshold		9	10		V
Hysteresis		2.5	3	3.5	V

ELECTRICAL CHARACTERISTICS: Unless otherwise stated, all specifications are over the junction temperature range of –55°C to +125°C for the UC1848, –40°C to +85°C for the UC2848, and 0°C to +70°C for the UC3848. Test conditions are: VCC = 12V, CT = 400pF, CI = 100pF, IOFF = 100µA, CDC = 100nF, Cvs = 100pF, and Ivs = 400µA, $T_A = T_J$.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
UV Comparator					
Turn-on Threshold		4.1	4.35	4.6	V
$R_{HYSTERESIS}$	Vuv = 4.2V	77	90	103	kΩ
Reference					
VREF	T_A = 25°C	4.95	5	5.05	V
	0 < I_O < 10mA, 12 < VCC < 20	4.93		5.07	V
Line Regulation	12 < V_{CC} < 20V		4	15	mV
Load Regulation	0 < I_O < 10mA		3	15	mV
Short Circuit Current	V_{REF} = 0V	30	50	70	mA
Output Stage					
Rise & Fall Time (Note 1)	Cl = 1nF		20	45	ns
Output Low Saturation	I_O = 20mA		0.25	0.4	V
	I_O = 200mA		1.2	2.2	V
Output High Saturation	I_O = -200mA		2.0	3.0	V
UVLO Output Low Saturation	I_O = 20mA		0.8	1.2	V
Icc					
I_{START}	VCC = 12V		0.2	0.4	mA
I_{CC} (pre-start)	VCC = 15V, V(UV) = 0		0.5	1	mA
I_{CC} (run)			22	26	mA

Note 1: Ensured by design.

APPLICATION INFORMATION

Under Voltage Lockout

The Under Voltage Lockout block diagram is shown in Fig 1. The VCC comparator monitors chip supply voltage. Hysteretic thresholds are set at 13V and 10V to facilitate off-line applications. If the VCC comparator is low, ICC is low (<500µA) and the output is low.

The UV comparator monitors input line voltage (V_{IN}). A pair of resistors divides the input line to UV. Hysteretic input line thresholds are programmed by Rv1 and Rv2. The thresholds are

V_{IN}(on) = 4.35V • (1 + Rv1/Rv2′) and

V_{IN}(off) = 4.35V • (1 + Rv1/Rv2) where

Rv2′= Rv2||90k.

The resulting hysteresis is

V_{IN}(hys) = 4.35V • Rv1 / 90k.

When the UV comparator is low, I_{CC} is low (500µA) and the output is low.

When both the UV and VCC comparators are high, the internal bias circuitry for the rest of the chip is activated. The CDC pin (see discussion on Maximum Duty Cycle Control and Soft Start) and the Output are held low until VREF exceeds the 4.5V threshold of the VREF comparator. When VREF is good, control of the output driver is transferred to the PWM circuitry and CDC is allowed to charge.

If any of the three UVLO comparators go low, the UVLO latch is set, the output is held low, and CDC is discharged. This state will be maintained until all three comparators are high and the CDC pin is fully discharged.

APPLICATION INFORMATION (cont.)

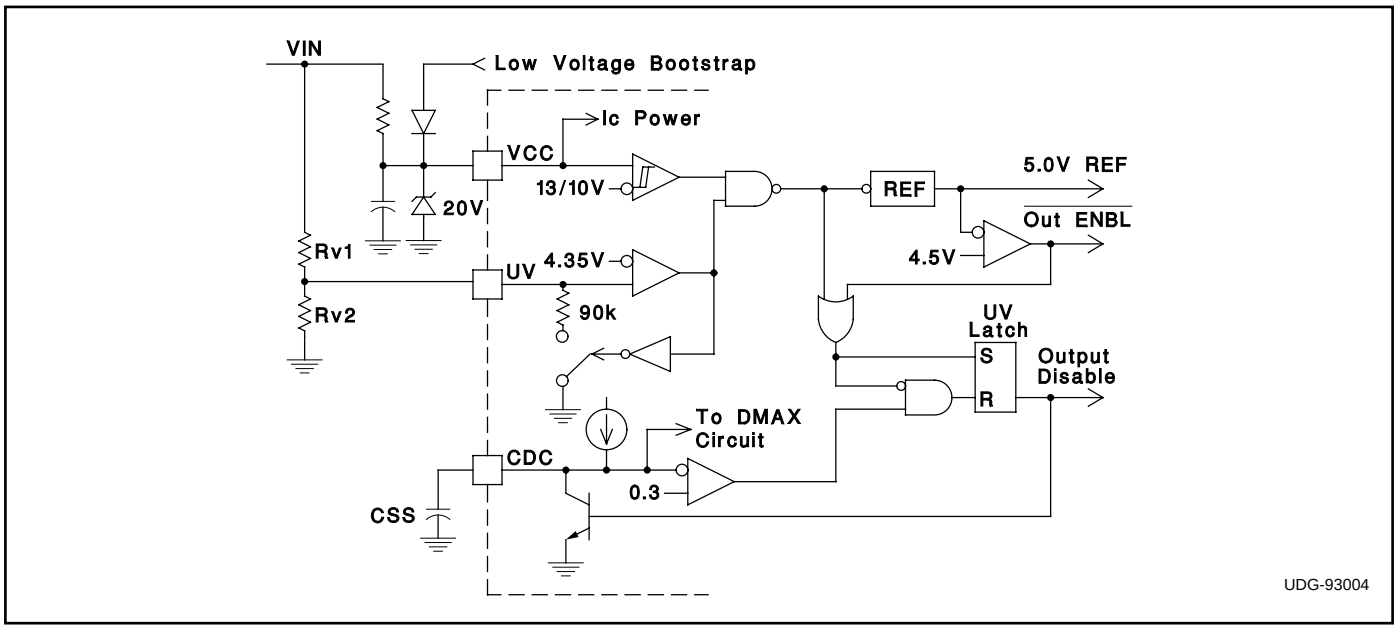


Figure 1: Under voltage lockout.

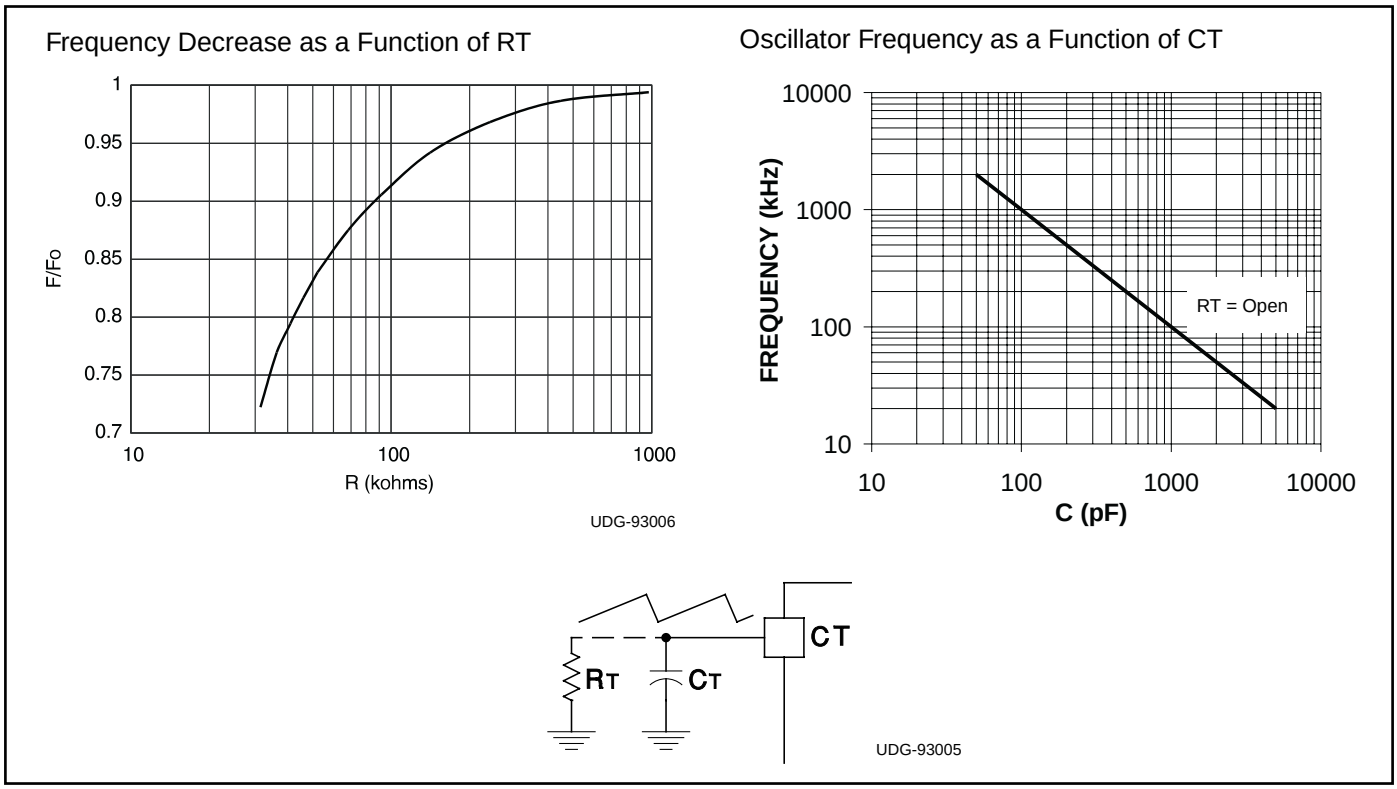


Figure 2: Oscillator frequency.

APPLICATION INFORMATION (cont.)

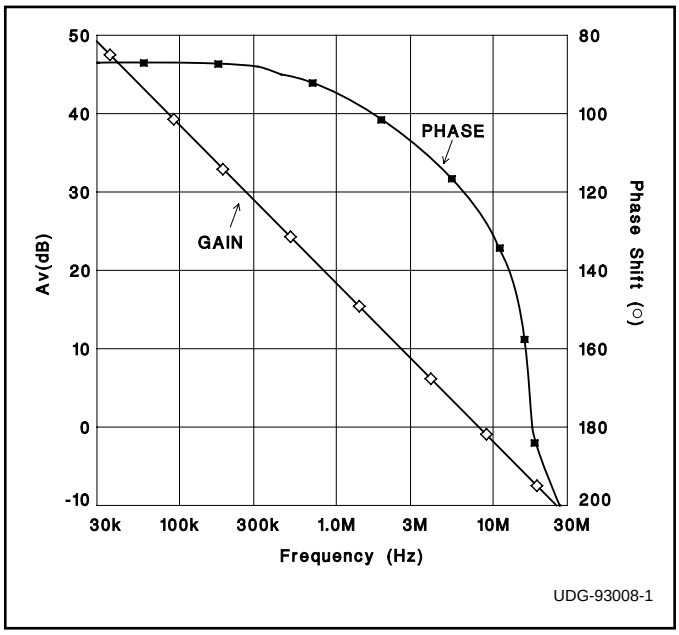


Figure 3: Error amplifier gain and phase response over frequency.

Oscillator

A capacitor from the CT pin to GND programs oscillator frequency, as shown in Fig. 2. Frequency is determined by:

F = 1 / (10k CT).

The sawtooth wave shape is generated by a charging current of 200 A and a discharge current of 1800 A. The discharge time of the sawtooth is guaranteed dead time for the output driver. If the maximum duty cycle control is defeated by connecting DMAX to VREF, the maximum duty cycle is limited by the oscillator to 90%. If an adjustment is required, an additional trim resistor RT from CT to Ground can be used to adjust the oscillator frequency. RT should not be less than 40k . This will allow up to a 22% decrease in frequency.

Inductor Current Waveform Synthesizer

Average current mode control is a very useful technique to control the value of any current within a switching converter. Input current, output inductor current, switch current, diode current or almost any other current can be controlled. In order to implement average current mode control, the value of the current must be explicitly known at all times. To control output inductor current (IL) in a buck derived isolated converter, switch current provides inductor current information, but only during the on time of the switch. During the off time, switch current drops abruptly to zero, but the inductor current actually diminishes with a slope dIL/dt = $-V_O/L$. This down slope must be synthesized in some manner on the primary side to provide the entire inductor current waveform for the control circuit.

The patented current waveform synthesizer (Fig. 4) consists of a unidirectional voltage follower which forces the voltage on capacitor CI to follow the on time switch current waveform. A programmable discharge current synthesizes the off time portion of the waveform. ION is the input to the follower. The discharge current is programmed at IOFF.

The follower has a one volt offset, so that zero current corresponds to one volt at CI. The best utilization of the UC3848 is to translate maximum average inductor current to a 4V signal level. Given N and Ns (the turns ratio of the power and current sense transformers), proper scaling of IL to V(CI) requires a sense resistor Rs as calculated from:

Rs = 4V Ns N / IL(max).

Restated, the maximum average inductor current will be limited to:

IL(max) = 4V Ns N/Rs.

IOFF and CI need to be chosen so that the ratio of dV(CI)/dt to dIL/dt is the same during switch off time as on time. Recommended nominal off current is 100 A. This requires

CI = (100 A N Ns L) / (Rs V_O(nom))

where L is the output inductor value and V_O(nom) is the converter regulated output voltage.

There are several methods to program IOFF. If accurate average current control is required during short circuit operation, IOFF must track output voltage. The method shown in Fig. 4 derives a voltage proportional to V_{IN} D (Duty Cycle). (In a buck converter, output voltage is proportional to VIN D.) A resistively loaded diode connection to the bootstrap winding yields a square wave whose amplitude is proportional to VIN and is duty cycle modulated by the control circuit. Averaging this waveform with a filter generates a primary side replica of secondary regulated V_O. A single pole filter is shown, but in practice a two or three pole filter provides better transient response. Filtered voltage is converted by ROFF to a current to the IOFF pin to control CI down slope.

APPLICATION INFORMATION (cont.)

If the system is not sensitive to short circuit requirements, Figure 5 shows the simplest method of downslope generation: a single resistor (ROFF = 40k) from IOFF to VREF. The discharge current is then 100µA. The disadvantage to this approach is that the synthesizer continues to generate a down slope when the switch is off even during short circuit conditions. Actual inductor down slope is closer to zero during a short circuit. The penalty is that the average current is understated by an amount approximately equal to the nominal inductor ripple current. Output short circuit is therefore higher than the designed maximum output current.

A third method of generating IOFF is to add a second winding to the output inductor core (Fig. 6). When the power switch is off and inductor current flows in the free wheeling diode, the voltage across the inductor is equal to the output voltage plus the diode drop. This voltage is then transformed by the second winding to the primary side of the converter. The advantages to this approach are its inherent accuracy and bandwidth. Winding the second coil on the output inductor core while maintaining the required isolation makes this a more costly solution. In the example, ROFF = V_O / 100µA. The 4 • ROFF resistor is added to compensate the one volt input level of the IOFF pin. Without this compensation, a minor current foldback behavior will be observed.

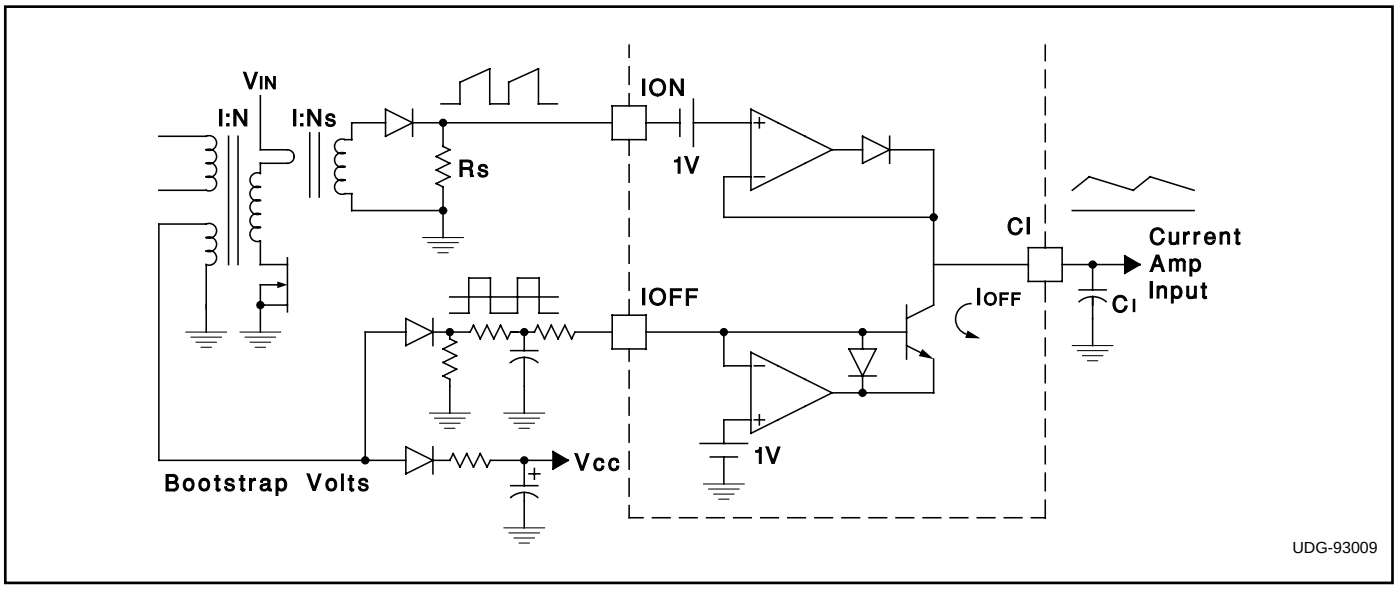


Figure 4: Inductor current waveform synthesizer.

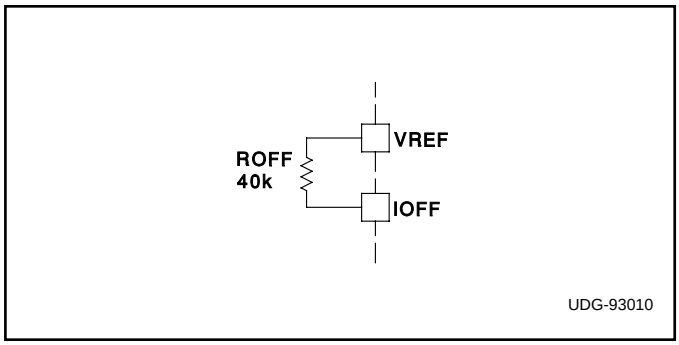


Figure 5: Fixed IOFF.

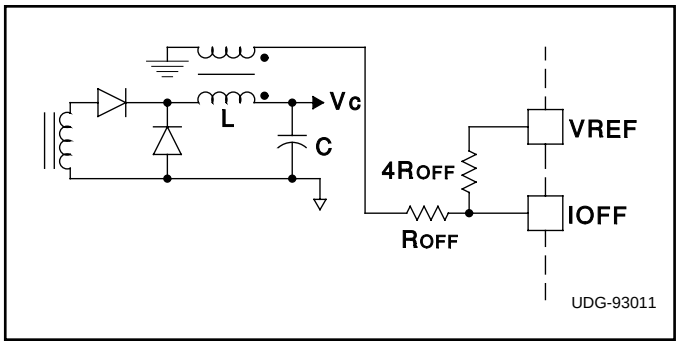


Figure 6: Second inductor winding generation of IOFF.

APPLICATION INFORMATION (cont.)

Maximum Volt-Second Circuit

A maximum volt-second product can be programmed by a resistor (Rvs) from VS to VIN and a capacitor (Cvs) from VS to ground (Figure 7). VS is discharged while the switch is off. When the output turns on, VS is allowed to charge. Since the threshold of the VS comparator is much less than VIN, the charging profile at Vs will be essentially linear. If VS crosses the 4.0V threshold before the PWM turns the output off, the VS comparator will turn the output off for the remainder of the cycle. The maximum volt-second product is

$V_{IN} \bullet T_{ON}(max) = 4.0V \bullet Rvs \bullet Cvs.$

Maximum Duty Cycle And Soft Start

A patented technique is used to accurately program maximum duty cycle. Programming is accomplished by a divider from VREF to DMAX (Fig. 7). The value programmed is:

$D(max) = Rd1 / (Rd1 + Rd2).$

For proper operation, the integrating capacitor, C_{DC}, should be larger than $C_{DC}(min) > T(osc) / 80k$, where T(osc) is the oscillator period. C_{DC} also sets the soft start time constant, so values of C_{DC} larger than minimum may be desired. The soft start time constant is approximately:

$T(ss) = 20k \bullet C_{DC}.$

Ground Planes

The output driver on the UC3848 is capable of 2A peak currents. Careful layout is essential for correct operation of the chip. A ground plane must be employed (Fig. 8). A unique section of the ground plane must be designated for high di/dt currents associated with the output stage. This point is the power ground to which to PGND pin is connected. Power ground can be separated from the rest of the ground plane and connected at a single point, although this is not strictly necessary if the high di/dt paths are well understood and accounted for. VCC should be bypassed directly to power ground with a good high frequency capacitor. The sources of the power MOSFET should connect to power ground as should the return connection for input power to the system and the bulk input capacitor. The output should be clamped with a high current Schottky diode to both VCC and PGND. Nothing else should be connected to power ground.

VREF should be bypassed directly to the signal portion of the ground plane with a good high frequency capacitor. Low esr/esl ceramic 1 F capacitors are recommended for both VCC and VREF. The capacitors from CT, CDC, and CI should likewise be connected to the signal ground plane.

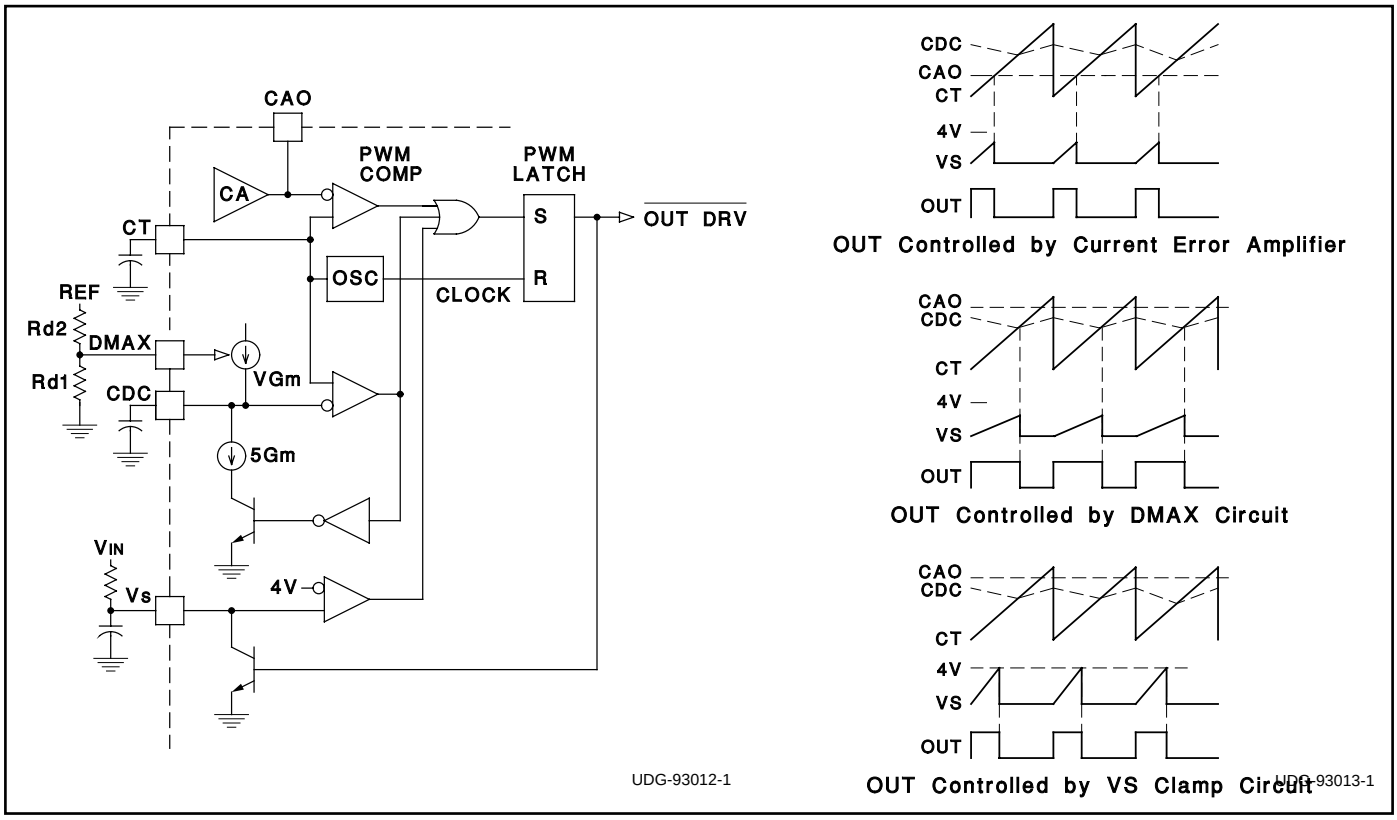


Figure 7: Duty cycle control.

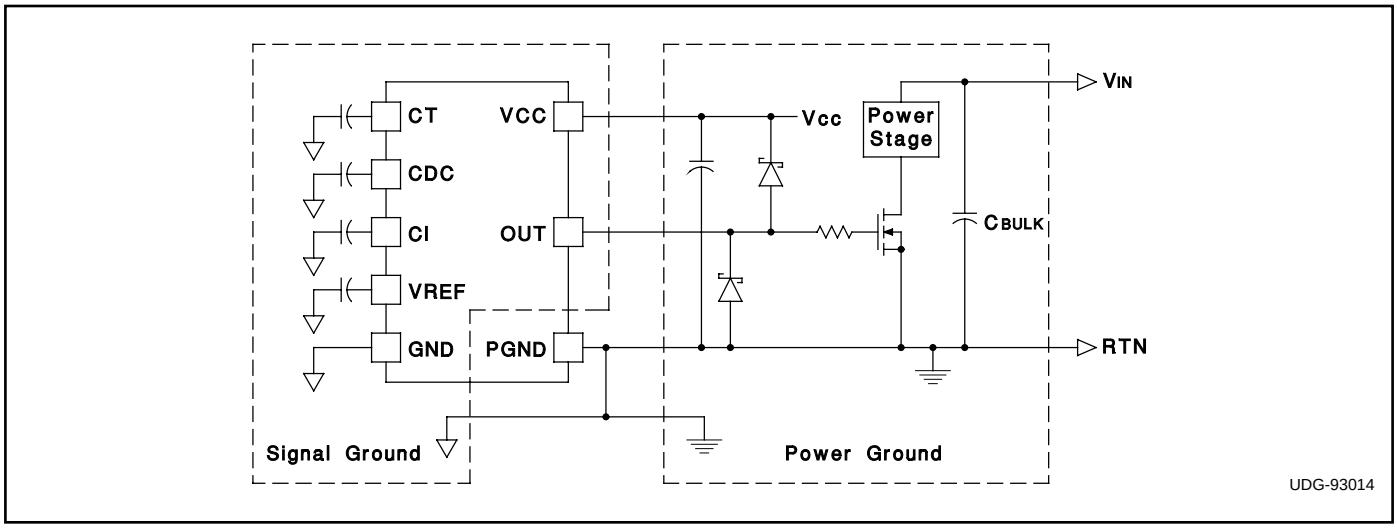


Figure 8: Ground plane considerations.

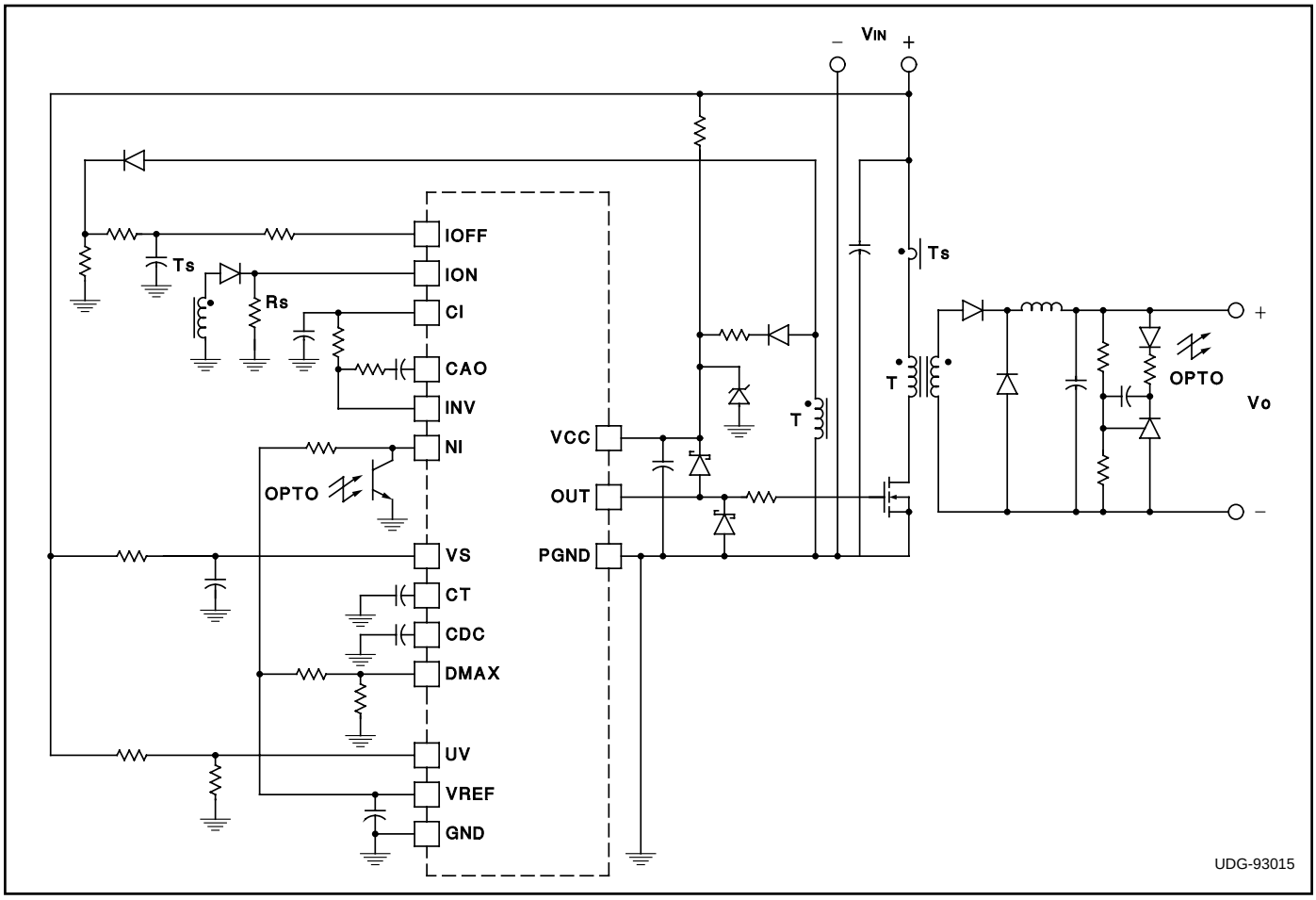


Figure 9: Typical application - an average current-mode isolated forward converter.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
UC1848J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
UC2848DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2848DWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2848J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
UC3848DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3848DWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3848DWTR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3848DWTRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3848N	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC3848NG4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type

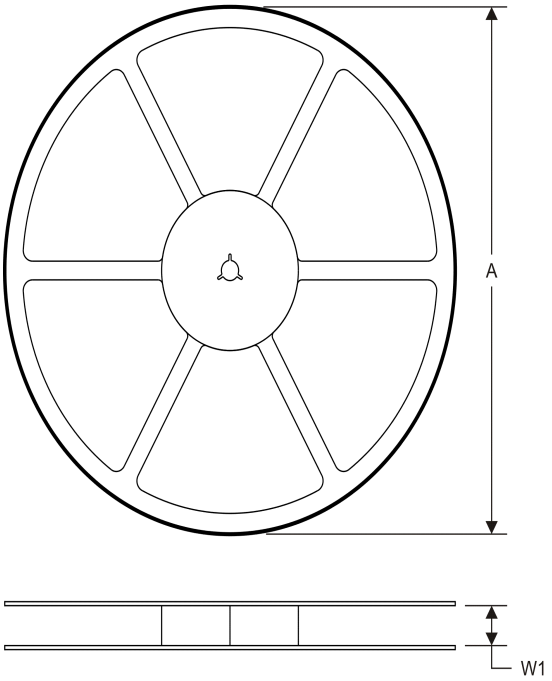
(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

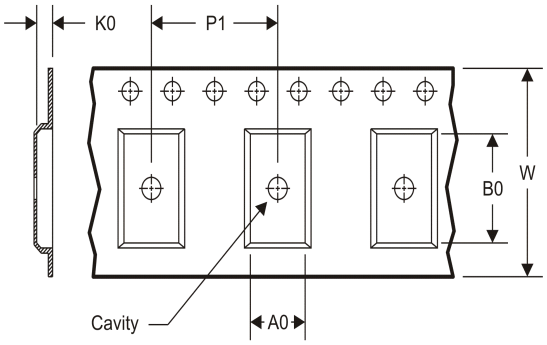
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



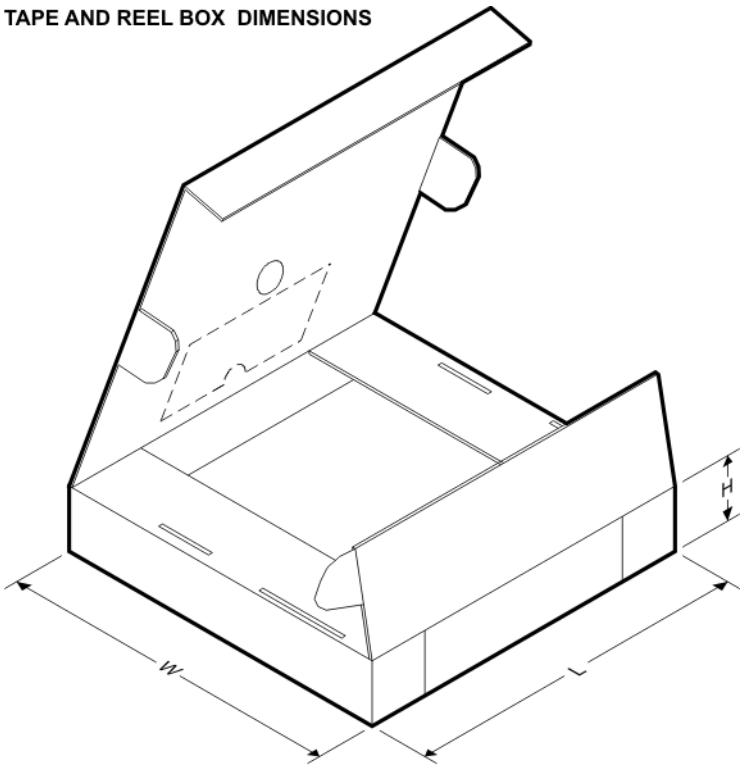
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UC3848DWTR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



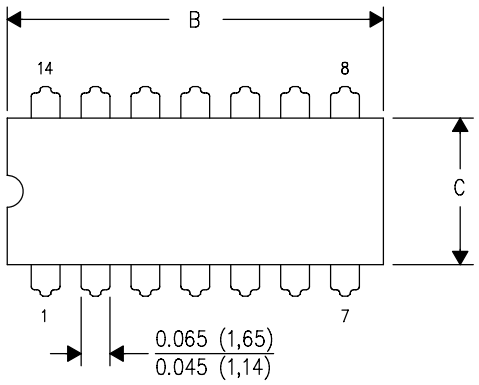
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UC3848DWTR	SOIC	DW	16	2000	367.0	367.0	38.0

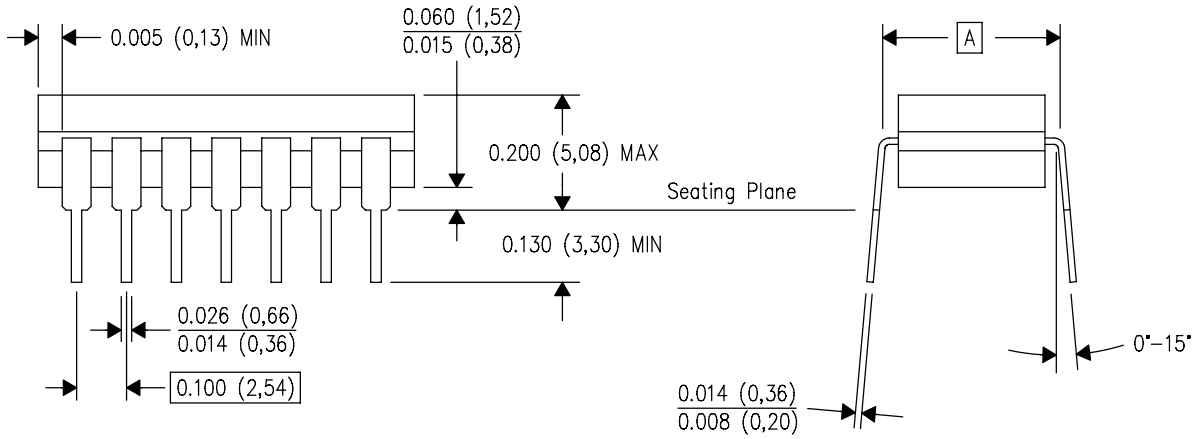
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



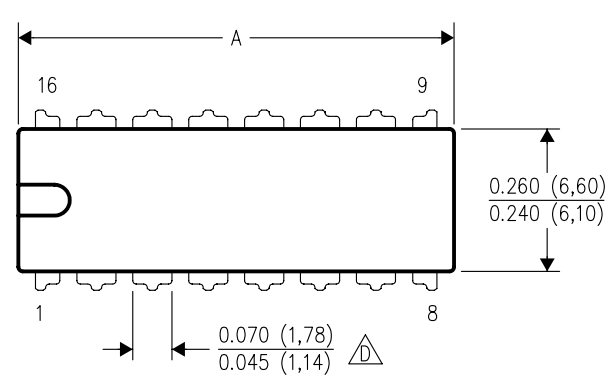
4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

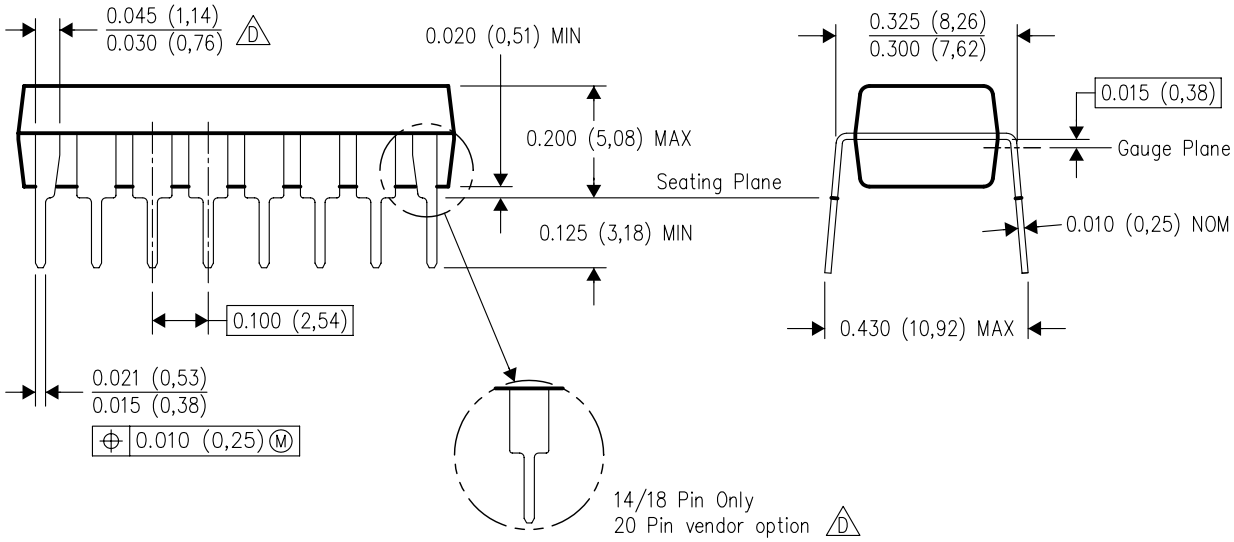
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



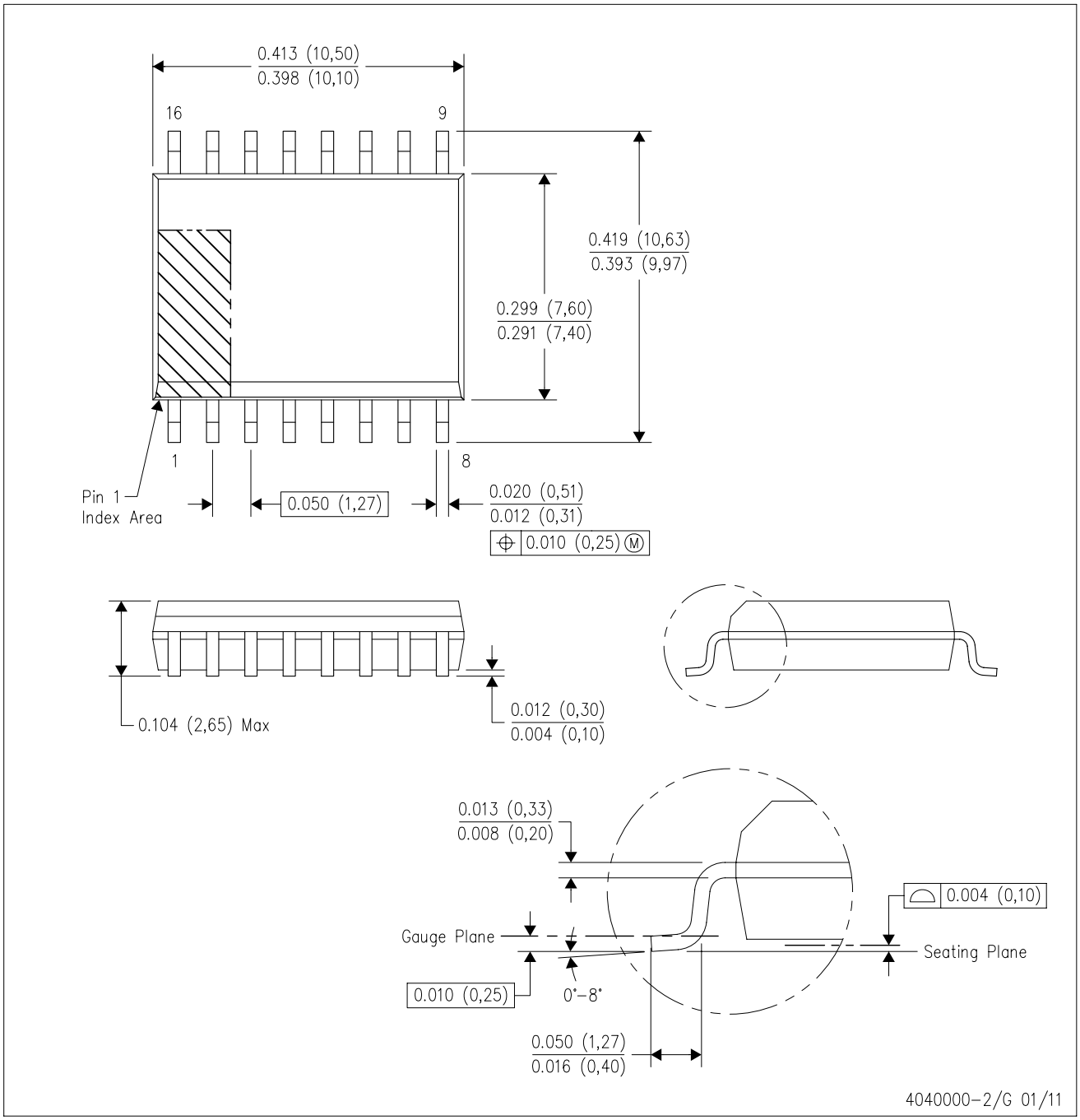
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

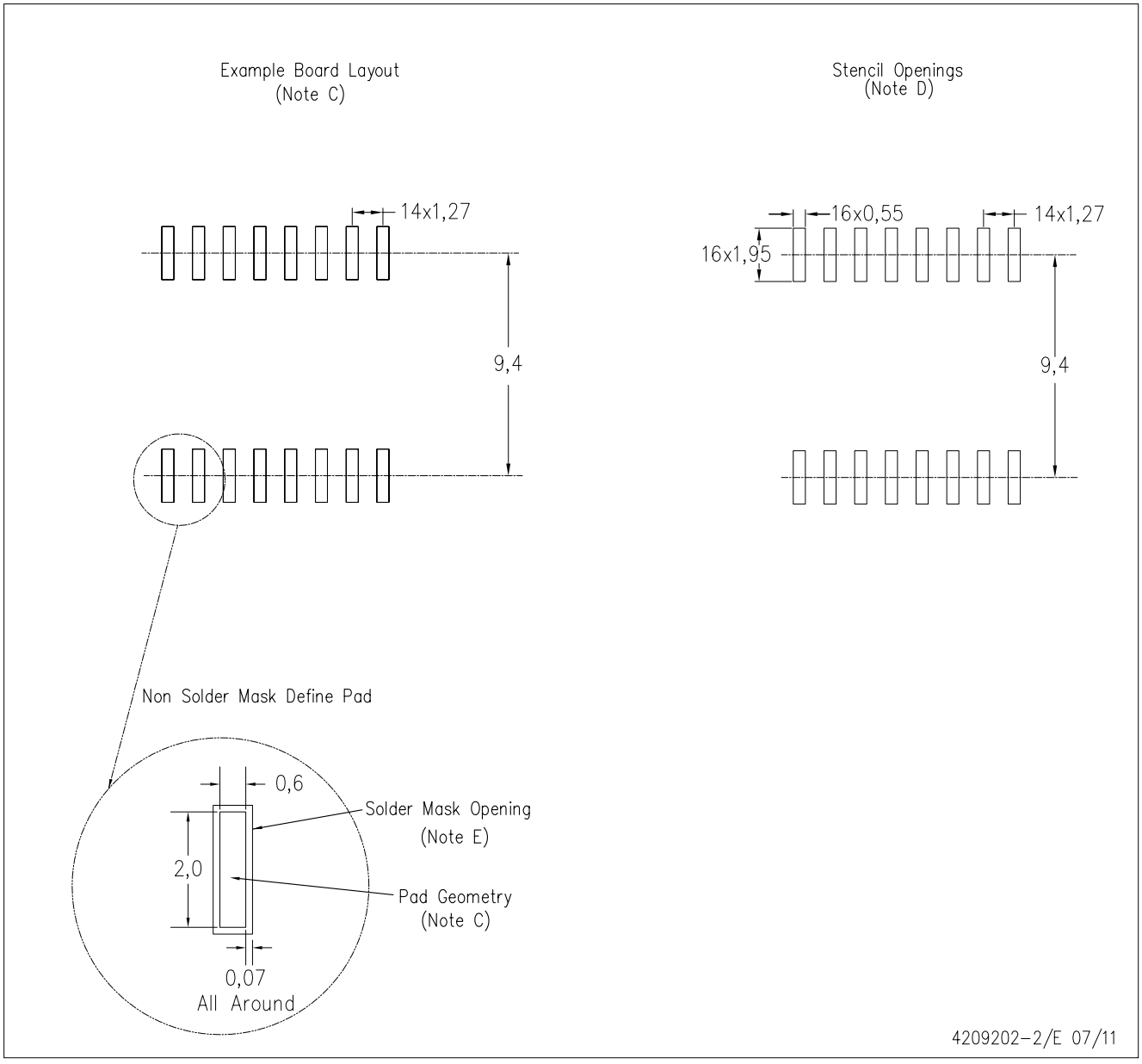
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–013 variation AA.

DW (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Refer to IPC7351 for alternate board design.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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